SPECIFICATIONS

CUSTOMER :	
SAMPLE CODE : GFG128064F-FPFA-01	
DRAWING NO. :	
DATE : <u>2009.03.02</u>	
CERTIFICATION: ROHS	

Customer Sign	Sales Sign	Approved By	Prepared By

Revision Record

Data(y/m/d)	Ver.	Description	Note	page
2009.03.02	00	New		17
2010.01.18	01	Revision B/L current		7

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1. SCOPE

This specification covers the engineering requirements for the GFG128064F-FPFA-01 liquid crystal module.

2. PRODUCT SPECIFICATIONS

- 2.1 General
 - 128 \$64 dot matrix LCD
 - FSTN, Positive mode LCD panel
 - Transflective, Normal temperature type
 - 6 o'clock
 - Back light: Edge LED (WHITE)
 - Multiplexing driving: 1/64duty, 1/9bias
 - Conteroller IC UC1601

2.2 Mechanical Characteristics

Item	Characteristic
Dot configuration	128 �64
Dot dimensions(mm)	0.399 \$0.431
Dot spacing (mm)	0.429 \$0.461
Module dimensions (Horizontal ❖ Vertical ❖Thickness, mm)	65
Viewing area (Horizontal ❖ Vertical, mm)	59 \$33.5
Active area (Horizontal &Vertical, mm)	54.882 \$29.474

2.3 Absolute
Maximum
Ratings
(Without LED

back-light)

Characteristic	Symbol	Unit	Value
Operating Voltage (logic)	$ m V_{DD}$	V	-0.3 to +4.0
Input Voltage	$\mathbf{V}_{\mathbf{IN}}$	V	-0.3 to V _{DD} +0.3

Note 1: Referenced to V_{SS}=0V

2.4 Electrical Characteristics (Without LED back-light)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Voo	Supply for digital circuit		2.4		3.3	V
$V_{DD2/3}$	Supply for bias & pump		2.4		3.3	V
V_{LCD}	Charge pump output	$V_{DD2/3} \ge 2.4 \text{V}, 25^{\circ}\text{C}$			11.5	V
V₀	LCD data voltage	$V_{DD2/3} \ge 2.4V, 25^{\circ}C$	0.80		1.32	V
VIL	Input logic LOW				0.2V _{DD}	V
ViH	Input logic HIGH		0.8V _{DD}			V
Vol	Output logic LOW				0.2V _{DD}	V
Voн	Output logic HIGH		0.8Vpp			V
ΙL	Input leakage current				1.5	μΑ
R _{0(SEG)}	SEG output impedance	V _{LCD} = 11V		2	3	kΩ
R ₀ (com)	COM output impedance	V _{LCD} = 11V		2	3	kΩ
F_{FR}	Average Frame Rate	LC[3] = 0b	66	76		Hz

2.5 Optical Characteristics Absolute maximum ratings

Item	Symbol	Rating	Unit

Operating temperature range	Тор	0~50	ФC
Storage temperature range	Tst	-20~70	ФC

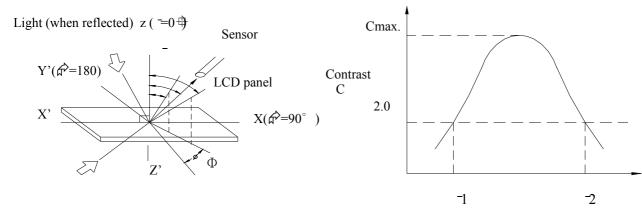
2.6 Optical Characteristics

1/64 duty, 1/9bias, Vop=10.2V, Ta=25°C

Item	Symbol	Conditions	Min.	Тур.	Max	Reference
Driving voltage	Vop=VDD-VO			10.2		
Viewing angle	-	C≥2.0,♠=0€€	30⊕			Notes 1 & 2
Contrast	С	-=5 \$ \$ =0 ⊕	3.0			Note 3
Response time(rise)	ton	-=5 \$ \$\div \div =0 \div			198ms	Note 4
Response time(fall)	toff	-=5 \$ \$ =0 ⊕			176ms	Note 4

Note 1: Definition of angles ⁻and ♠

Note 2: Definition of viewing angles ¬1 and ♠2



Light (when transmitted) $Y(\overrightarrow{R}=0^{\circ})$ ($=90^{\circ}$)

Note: Optimum viewing angle with the naked eye and viewing angle -at Cmax. Above are not always the same

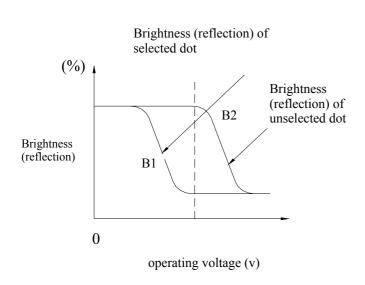
viewing angle $\neg(\Phi \text{ fixed})$

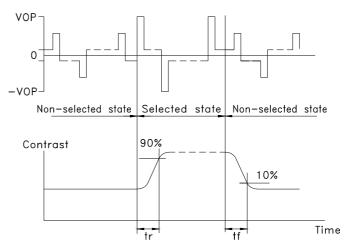
Note 3: Definition of contrast C

Brightness (reflection) of unselected dot (B2)

C = _____ Brightness (reflection) of selected dot (B1)

Note 4: Definition of response time





Note: Measured with a transmissive LCD panel which is displayed 1 cm²

 V_{OPR} : Operating voltage f_{FRM} : Frame frequency

t ON: Response time (rise) t OFF: Response time (fall)

2.7 LED Back-light Characteristics

2.7.1 Electrical / optical specifications

 $Ta = 25 \oplus \mathbb{C}$

			1a – 25			
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward voltage	V_{f}	If=60mA, WHITE	2.9	3.2	3.6	V
LED *Luminous Intensity	I_{V}	If=60mA, WHITE		120		Cd/m2
Chromaticity Coordinate	X	If=60mA, WHITE	0.26	0.31	0.36	
	y		0.25	0.32	0.37	
Reverse Current	I_R	VR=5V, WHITE			0.1	mA

Note: * Measured at the bare LED back-light unit.

2.7.2 LED Maximum Operating Range

Item	Symbol	WHITE	Unit
Power Dissipation	P_{AD}	216	mW
Forward Current	I_{F}	60	mA
Reverse Voltage	V_{R}	5	V

3. RELIABILITY

3.1 Reliability

Test item	Test condition	Evaluation and assessment
Operation at high temperature and humidity	40 °C ⊕2 °C 90%RH for 500hours	No abnormalities in functions* and appearance**
Operation at high temperature	50°C €2°C for 500 hours	No abnormalities in functions* and appearance**
Heat shock	0 →~ +50 °C Left for 1 hour at each temperature, transition time 5 min, repeated 10times	No abnormalities in functions* and appearance**
Low temperature	0⊕2°C for 500 hours	No abnormalities in functions* and appearance**
Vibration	Sweep for 1 min at 10 Hz, 55Hz, 10Hz, amplitude 1.5mm 2 hrs each in the X,Y and Z directions	No abnormalities in functions* and appearance**
Drop shock	Dropped onto a board from a height of 10cm	No abnormalities in functions* and appearance**

- * Dissipation current, contrast and display functions
- ** Polarizing filter deterioration, other appearance defects

3.2 Liquid crystal panel service life 100,000 hours minimum at 25 °C \$\phi 10 \cdot \cdot

- 3.3 definition of panel service life
 - Contrast becomes 30% of initial value
 - Current consumption becomes three times higher than initial value
 - Remarkable alignment deterioration occurs in LCD cell layer
 - Unusual operation occurs in display functions

4. OPERATING INSTRUCTIONS

4.1 Input signal Function

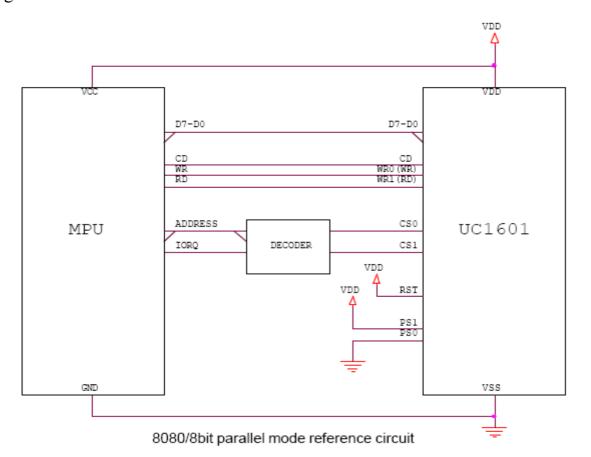
Pin No	Symbol	I/O	Function				
1~4	NC	-	No Conr	nection.			
5	V LCD	PWR	Main LC	D power supply.			
6	V B0+	PWR	LCD Bia	s Voltages. The	se are the voltag	ge sources to provide	
7	V B0-	PWR	SEG driv	SEG driving currents. These voltages are generated internally.			
8	V B1-	PWR	Connect	capacitors of C	3X value betwee	n VBX+ and VBX	
9	V B1+	PWR					
10	VSS	PWR	Power G	Power Ground.			
11	VDD	PWR	Power s	upply terminal V	CC.		
12	BM1	ı	Bus mode: "HL": 8080 "HH": 6800				
13	BM0	I	BM[1:0] "LH": S9 "LL": S8				
14	DB7	I/O	Bi-direct	tional bus for bot	th serial and par	allel host interfaces.	
15	DB6	I/O	In serial modes, connect DB0 to SCK, DB3 to SDA.				
16	DB5	I/O		BM=1x	BM=0x	1	
17	DB4	I/O		(Parallel)	(Serial)	1	
18	DB3/SDA	I/O	D0 D1	D0 D1	SCK		
19	DB2	I/O	D2	D2			
20	DB1	I/O	D3	D3	SDA		
21	DB0/SCK	I/O	D4 D5	D4 D5			
			D6	D6	-		
			D7	D7	-	J	
22	WR1	ı	WR [1:0]	controls the rea	d/write operatio	n of the host	
23	WR0	ı	interface	e. See Host Interf	ace section for	details. The meaning	
			of WR [1:0] depends on whether the interface is in the 6800				
			mode, or the 8080 mode. In serial modes, these two pins are				
			not used and can be connected to Vss.				
24	CD	I	Select th	ne incoming com	mand if it is a co	ontrol instruction or	

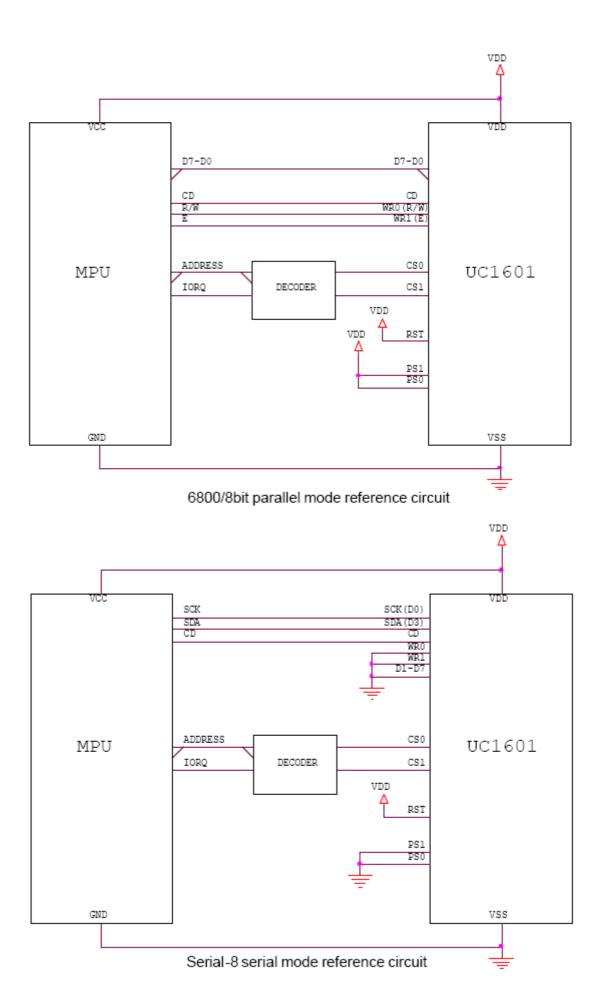
			for display data. CD pin is not used in S9 mode, connect it to Vdd or Vss. " L": control instruction "H": display data
25	RST	I	When RST="L", all control registers are re-initialized by their default states.
26	/CS0	I	Chip Select or Chip Address. In parallel mode and S8 mode, chip is selected when /CS0="L". When the chip is not selected, DB[7:0] will be high impedance.
27~30	NC	-	No Connection.

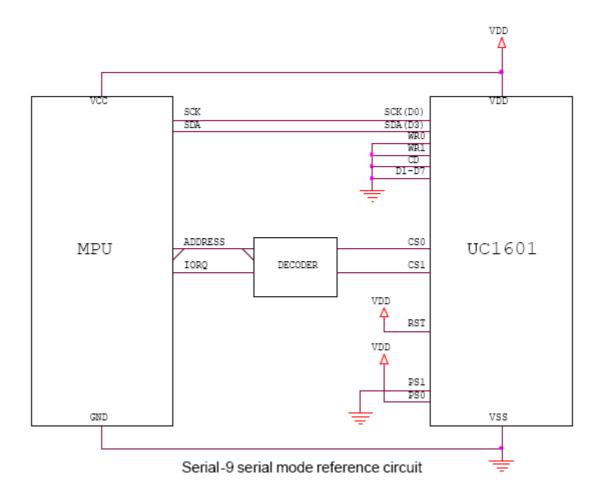
В	us Type	8080	6800	SPI (S8)	SPI (S9)
"	BM[1:0]	10b	11b	00b	01b
Pins	CS[1:0]		Chip	Select	
Data F	CD		Control/Data		_
& Da	WR0	WR	R/W	-	_
Control 8	WR1	RD	EN	-	_
, ou	Access	Read	Write	Write	Only
0	D[7:0]	8-bit bus	(Tri-state)	D0=SCK	, D3=SDA

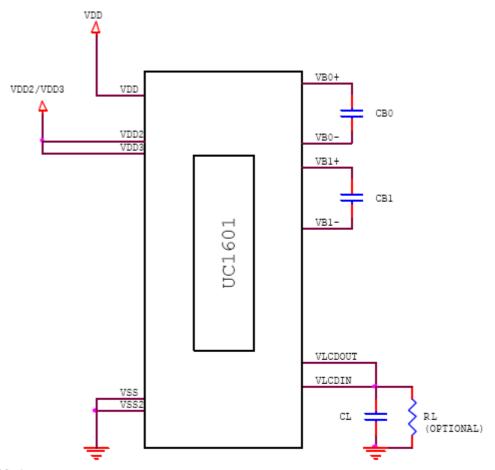
^{*} Connect unused control pins and data bus pins to V_{DD} or V_{SS}

4.2 Voltage Generator Circuit









Note

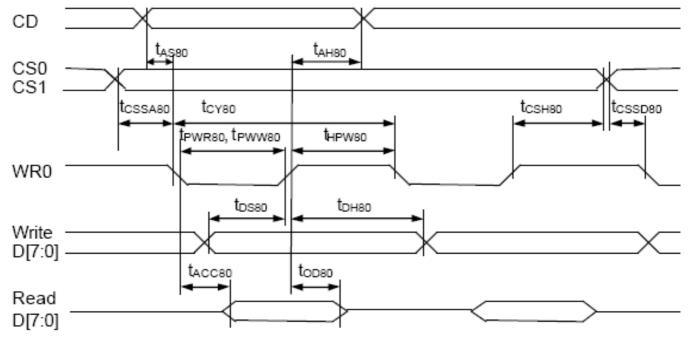
Recommended component values:

C_B: 100x~200x LCD load capacitance or 1.0uF (2V), whichever is higher.

 C_L : 10nF ~ 30nF (25V) is appropriate for most applications.

 $R_L\colon\ 10M\Omega$, Acts as a draining circuit when the power is abnormally shut down,

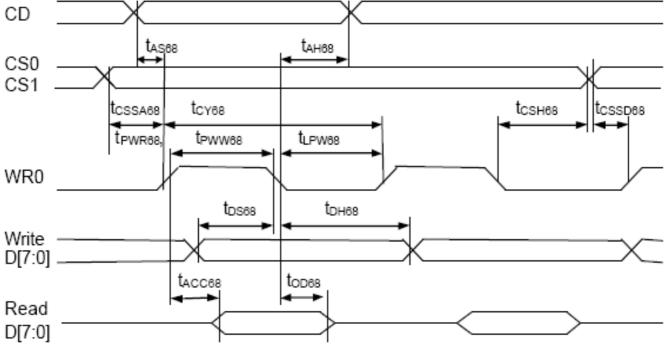
4.3 Timing Diagram



Parallel Bus Timing Characteristics (for 8080 MCU)

 $(2.5V \le V_{DD} < 3.3V, Ta = -30 \text{ to } +85\degree\text{C})$

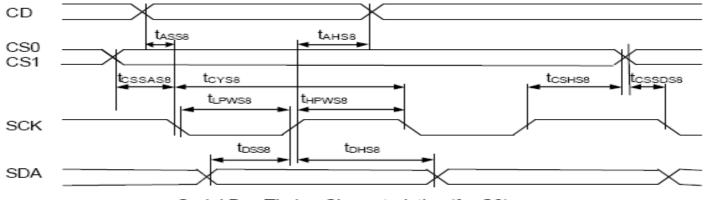
Symbol	Signal	Description	Condition	Min.	Max.	Units
taseo	CD	Address setup time		0	-	nS
t _{ahbo}	CD	Address hold time		40		
t _{CY80}		System cycle time		135	-	nS
t _{PWR80}	WR1	Pulse width (read)		65	-	nS
t _{PWW80}	WR0	Pulse width (write)		65	-	nS
t _{HPW80}	WR0, WR1	High pulse width		65	_	nS
t _{DS80}	D0~D7	Data setup time		30	-	nS
t _{DH80}	D0~D1	Data hold time		20		
t _{ACC80}		Read access time	C _L = 100pF	_	50	nS
topso		Output disable time		10	50	
tcssa80				10		nS
tcsspeo	CS1/CS0	Chip select setup time		10		
t _{csH80}				20		



Parallel Bus Timing Characteristics (for 6800 MCU)

 $(2.5V \le V_{DD} < 3.3V, Ta = -30 \text{ to } +85^{\circ}C)$

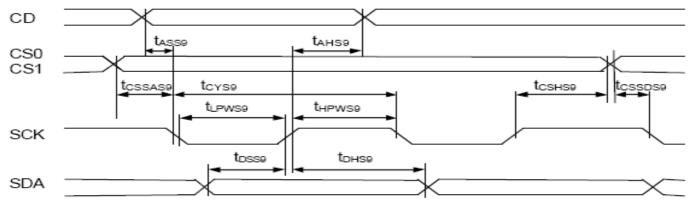
Symbol	Signal	Description	Condition	Min.	Max.	Units
t _{aseb}	CD	Address setup time		0	-	nS
t _{ah68}		Address hold time		40		
t _{CY68}		System cycle time		135	-	nS
t _{PWR68}	WR1	Pulse width (read)		65	-	nS
t _{PWW68}		Pulse width (write)		65	-	nS
tlpw68		Low pulse width		65	-	nS
t _{DS88}	D0~D7	Data setup time		30	-	nS
tонвя		Data hold time		15		
t _{ACC88}		Read access time	C _L = 100pF	_	50	nS
t _{opes}		Output disable time		10	50	
Tcssa68	CS1/CS0			10		nS
T _{CSSD68}		Chip select setup time		10		
T _{CSH88}				20		



Serial Bus Timing Characteristics (for S8)

 $(2.5V \le V_{DD} < 3.3V, Ta = -30 \text{ to } +85^{\circ}C)$

Symbol	Signal	Description	Condition	Min.	Max.	Units
tassb	CD	Address setup time		0	_	nS
t _{ahs8}	CD	Address hold time		40	_	nS
t _{CYS8}		System cycle time		135	_	nS
t _{LPWS8}	SCK	Low pulse width		65	_	nS
t _{HPWS8}		High pulse width		65	_	nS
tossa	SDA	Data setup time		30	_	nS
t _{DHS8}	SDA	Data hold time		15		
tcssas8				10		nS
tcssps8	CS1/CS0	Chip select setup time		10 20		
tcsHs8				∠0		



Serial Bus Timing Characteristics (for S9)

$$(2.5V \le V_{DD} < 3.3V, Ta = -30 \text{ to } +85^{\circ}C)$$

Symbol	Signal	Description	Condition	Min.	Max.	Units
tasse	CD	Address setup time		0	_	nS
t _{AHS9}	OD	Address hold time		40	_	nS
t _{CYS9}		System cycle time		135	_	nS
t _{LPWS9}	SCK	Low pulse width		65	_	nS
t _{HPWS9}		High pulse width		65	_	nS
tosse touse	SDA	Data setup time Data hold time		30 15	-	nS
tcssase tcsspse tcsase	CS1/CS0	Chip select setup time		10 10 20		nS

5. NOTES

Safety

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• If the LCD panel breaks, be careful not to get the liquid crystal in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and plenty of water.

Handling

- Avoid static electricity as this can damage the CMOS LSI.
- The LCD panel is plate glass; do not hit or crush it.
- Do not remove the panel or frame from the module.
- The polarizing plate of the display is very fragile; handle it very carefully

Mounting and Design

- Mount the module by using the specified mounting part and holes.
- To protect the module from external pressure, leave a small gap by placing transparent plates (e.g. acrylic or glass) on the display surface, frame, and polarizing plate
- Design the system so that no input signal is given unless the power-supply voltage is applied.
- Keep the module dry. Avoid condensation, otherwise the transparent electrodes may break.

Storage

- Store the module in a dark place where the temperature is 25 °C ⊕10 °C and the humidity below 65% RH.
- Do not store the module near organic solvents or corrosive gases.
- Do not crush, shake, or jolt the module (including accessories).

Cleaning

- Do not wipe the polarizing plate with a dry cloth, as it may scratch the surface.
- Wipe the module gently with soft cloth soaked with a petroleum benzine.
- Do not use ketonic solvents (ketone and acetoe) or aromatic solvents (toluene and xylene), as they may damage the polarizing plate.

6. OPERATION PRECAUTIONS

Any changes that need to be made in this specification or any problems arising from it will be dealt with quickly by discussion between both companies.

7. LCM Dimension

